

# MS1V-T1K Product Documentation

# Product Documentation

MS1V-T1K

Quartz Crystal Unit 32.768 kHz

February 2017 1/12 Rev. 1.0

#### 2. Product Description

The MS1V-T1K is a low frequency surface mount technology Quartz Crystal Unit that incorporates a tuning fork Quartz Crystal Resonator. The Quartz Crystal Resonator operates under vacuum condition in a hermetically sealed square-bodied metal can package.

Suitable oscillator-circuitries can operate the MS1V-T1K Quartz Crystal Units in fundamental mode consuming very low power. For technical assistance for optimizing oscillator-circuitries please contact Micro Crystal under <a href="mailto:sales@microcrystal.com">sales@microcrystal.com</a>

#### 2.1. Application Examples

IoT Metering Wearables Health Care Consumer Electronics

#### 2.2. Ordering Information

Example: MS1V-T1K 32.768 kHz CL: 12.5 pF -20/+20ppm TA QC Au

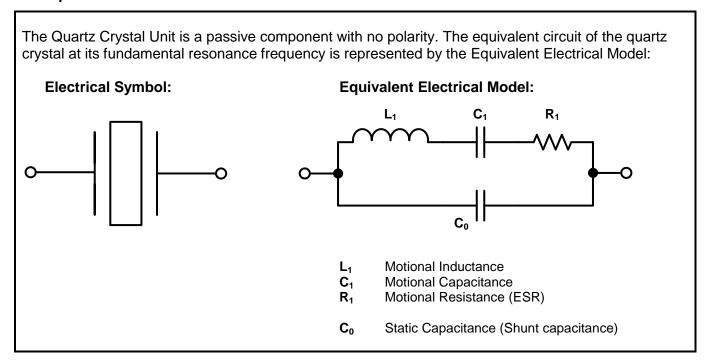
Code	Operating temperature range
TA (Standard)	-40 to +85°C

Code	Qualification
QC (Standard)	Commercial Grade

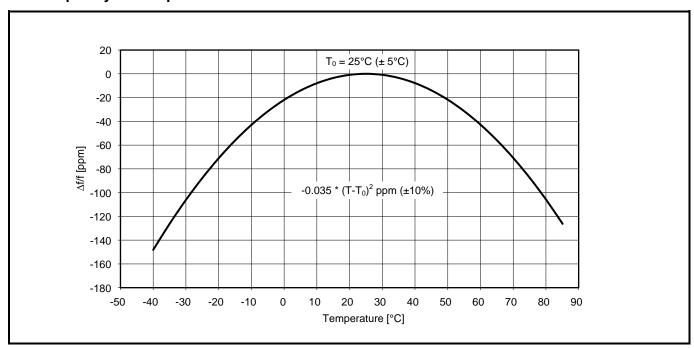
Code	Can
Au	Au flashed

#### 3. Electrical Characteristics

#### 3.1. Equivalent Electrical Model

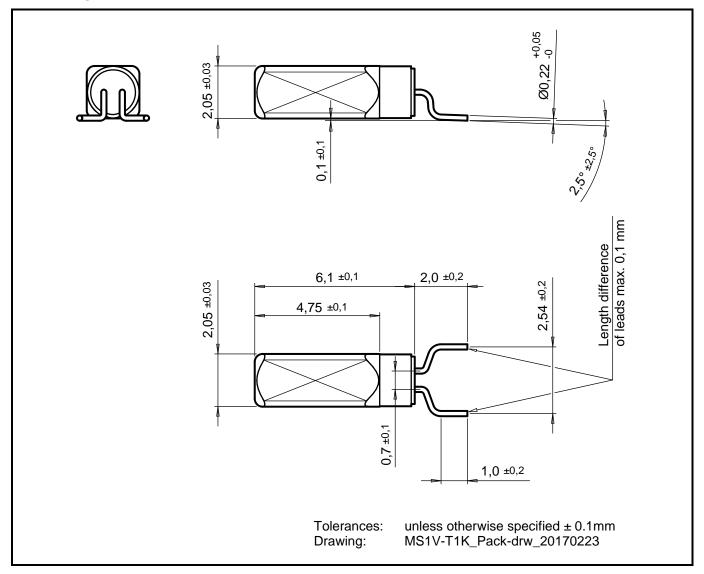


#### 3.2. Frequency vs Temperature Characteristics

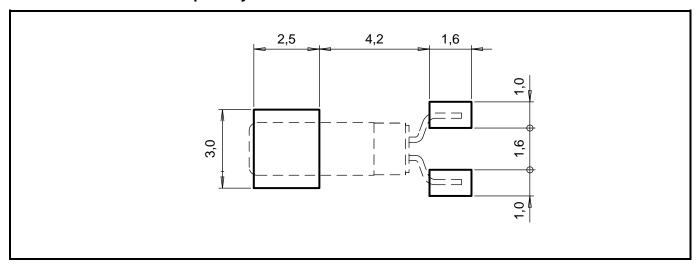


# 4. Mechanical Properties

# 4.1. Package Dimension



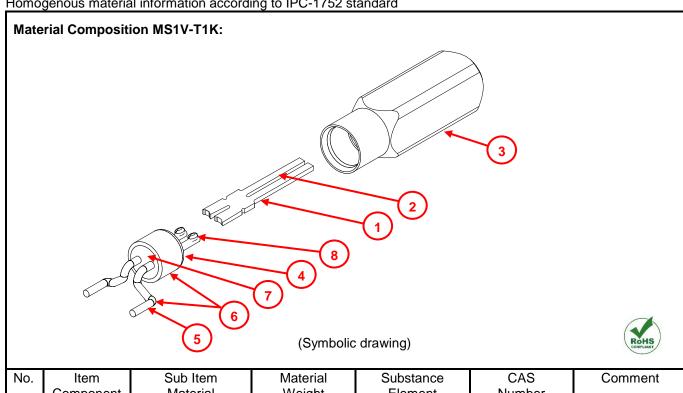
# 4.2. Recommended Solderpad Layout



# 5. Material Composition Declaration & Environmental Information

#### 5.1. Homogenous Material Composition Declaration

Homogenous material information according to IPC-1752 standard



No.	Item Component	Sub Item Material	Mate Wei		Substance Element	CAS Number	Comment
	Name	Name	(mg)	(%)			
1	Resonator	Quartz Crystal	0.65	100%	SiO <sub>2</sub>	14808-60-7	
2	Electrodes	Cr+Au	0.01	6% 94%	Cr Au	7440-47-3 7440-57-5	
3	Сар	Brass	94.1	99.3%	Cu58Zn39Pb3	12597-71-6	Pb RoHS exempt in copper alloys up to 4% (exemption (6(c))
		Ni-plating		0.6%	Ni, 1 micron	Ni: 7440-02-0	
		Au-plating		0.1%	Au, 0.05 micron	Au: 7440-57-5	
4	Holder ring	Alloy 42		100%	Fe57Ni42Mn1	Fe: 7439-89-6	
			5.5			Ni: 7440-02-0	
						Mn: 7439-96-5	
5	Leads	Kovar		100%	Fe53Ni29Co18	Fe: 7439-89-6	
			1.5			Ni: 7440-02-0	
						Co: 7440-48-4	
6	Lead plating	Cu-plating		13%	Cu, 2 micron	7440-50-8	
		Solder-plating		71%	Pb93Sn7, 9 micron	Pb: 7439-92-1	Pb RoHS exempt in
			1.5			Sn: 7440-31-5	high temperature solder with more than 85% lead (exemption 7(a))
		Ag-plating		15%	Ag, 2 micron	Ag: 7440-22-4	
		Au-flashed		1%	Au, 0.1 micron	Au: 7440-57-5	
7	Seal	Glass	6.0	100%	SiO <sub>2</sub>	65997-17-3	
8	Resonator	Silver filled Epoxy	0.075	30%	Epoxy resin	129915-35-1	
	attach		0.075	70%	Ag	7440-22-4	
		Unit weight	109.3				

#### 5.2. Material Analysis & Test Results

Homogenous material information according to IPC-1752 standard

No.	Item Component	Sub Item  Material		RoHS			Halogen			Phthalates						
	Name	Name	Pb	рЭ	ВH	Cr+6	PBB	PBDE	Ь	IO	Br	1	ВВР	A80	DEHP	DINP
1	Resonator	Quartz Crystal	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
2	Electrodes	Cr+Au	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
3	Сар	Brass		RoHS 5 ppm	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
4	Holder ring	Alloy 42	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
5	Leads	Kovar	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
6	Lead plating	Cu+SnPb+Ag+Au	RoHS 92.34%	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
7	Seal	Glass	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
8	Resonator attach	Silver filled Epoxy	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd	nd
	MDL	Measurement Detection Limit		2 p	pm		5 p	pm		50 p	opm		C	0.003%	6	0.01%

nd = not detectable

RoHS = RoHS compliant, substances accepted by RoHS Directive.

Test methods:

**RoHS** Test method with reference to IEC 62321-5: 2013 MDL: 2 ppm (PBB / PBDE: 5 ppm)

Halogen Test method with reference to BS EN 14582:2007 MDL: 50 ppm

**Phthalates** Test method with reference to EN 14372 MDL: 0.003 % (DINP 0.01%)

#### 5.3. Recycling Material Information

Recycling material information according to IPC-1752 standard.

Item	No.	Item		erial	Substance	CAS	Comment
Material Name		Component Name		ight (%)	Element	Number	
Quartz Crystal	1	Resonator	(mg) 0.65	0.59	SiO <sub>2</sub>	14808-60-7	
Chromium	2	Electrodes	0.0006	0.0005	Cr	7440-47-3	
Brass	3	Cap	93.44	85.46	Cu58Zn39Pb3	12597-71-6	
Gold	2 3 6	Electrodes Cap Lead plating	0.12	0.11	Au	7440-57-5	
Nickel	3	Сар	0.56	0.52	Ni	Ni: 7440-02-0	
Alloy 42	4	Holder ring	5.50	5.03	Fe57Ni42Mn1	Fe: 7439-89-6 Ni: 7440-02-0 Mn: 7439-96-5	
Kovar	5	Leads	1.50	1.37	Fe53Ni29Co18	Fe: 7439-89-6 Ni: 7440-02-0 Co: 7440-48-4	
Copper	6	Lead plating	0.20	0.18	Cu	7440-50-8	
Solder SnPb	6	Lead plating	1.06	0.97	Pb93Sn7	Pb: 7439-92-1 Sn: 7440-31-5	
Silver	6 8	Lead plating Resonator attach	0.28	0.25	Ag	7440-22-4	
Glass	7	Seal	6.00	5.49	SiO <sub>2</sub>	65997-17-3	
Ероху	8	Resonator attach	0.02	0.02	Epoxy resin	129915-35-1	
	Unit v	weight (total)	109.3	100			

# 5.4. Environmental Properties & Absolute Maximum Ratings

Package	Description
Metal Package	Hermetic metal-package, with formed leads.

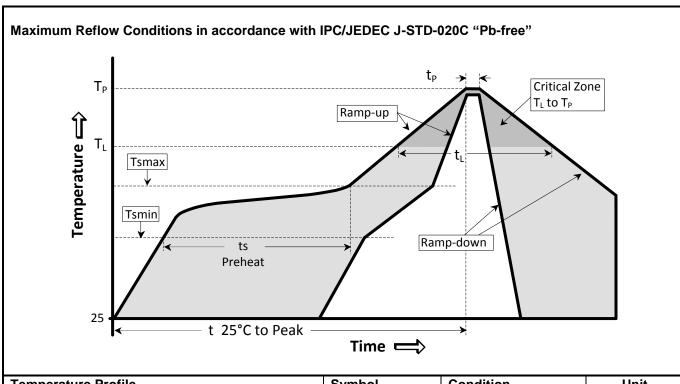
Parameter	Directive	Conditions	Value
Product weight (total)			109.3 mg
Storage temperature		Store as bare product	-55 to +125°C
Moisture sensitivity level (MSL)	IPC/JEDEC J-STD-020D		MSL 1
FIT / MTBF			available on request

Finish for Holder ring and Leads:



# 6. Application Information

# 6.1. Soldering Information



Temperature Profile	Symbol	Condition	Unit
Average ramp-up rate	(Ts <sub>max</sub> to T <sub>P</sub> )	3°C / second max	°C/s
Ramp down Rate	T <sub>cool</sub>	6°C / second max	°C/s
Time 25°C to Peak Temperature	T <sub>to-peak</sub>	8 minutes max	min
Preheat			
Temperature min	Ts <sub>min</sub>	150	°C
Temperature max	Ts <sub>max</sub>	200	°C
Time Ts <sub>min</sub> to Ts <sub>max</sub>	ts	60 – 180	sec
Soldering above liquidus			
Temperature liquidus	T∟	217	°C
Time above liquidus	t∟	60 – 150	sec
Peak temperature			
Peak Temperature	Тр	260	°C
Time within 5°C of peak temperature	tp	20 – 40	sec

#### 6.2. Handling Instructions for Quartz Crystal Units

The built-in tuning-fork crystal consists of pure Silicon Dioxide in crystalline form. The cavity inside the package is evacuated and hermetically sealed in order for the crystal blank to function undisturbed from air molecules, humidity and other influences.

#### Shock and vibration:

Keep the crystal / module from being exposed to **excessive mechanical shock and vibration**. Micro Crystal guarantees that the crystal / module will bear a mechanical shock of 5000 g / 0.3 ms.

The following special situations may generate either shock or vibration:

**Multiple PCB panels -** Usually at the end of the pick & place process the single PCBs are cut out with a router. These machines sometimes generate vibrations on the PCB that have a fundamental or harmonic frequency close to 32.768 kHz. This might cause breakage of crystal blanks due to resonance. Router speed should be adjusted to avoid resonant vibration.

**Ultrasonic cleaning -** Avoid cleaning processes using ultrasonic energy. These processes can damage crystals due to mechanical resonance of the crystal blank.

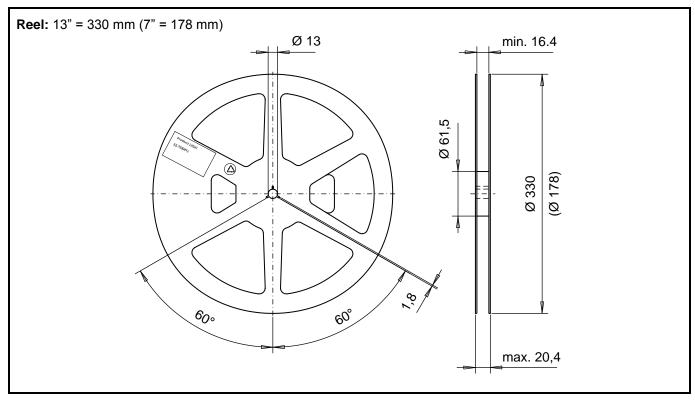
#### Overheating, rework high temperature exposure:

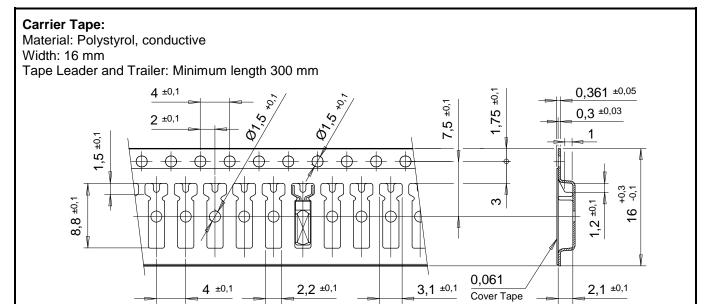
Avoid overheating the package. The package is sealed with a solder consisting of 93% Lead and 7% Tin. The melting temperature of this alloy is at 280°C. Heating the package up to >280°C will cause melting of the metal seal which then, due to the vacuum, is sucked into the cavity forming an air duct. This happens when using hot-air-gun set at temperatures >300°C.

Use the following method for rework:

Use a hot-air- gun set at 270°C.

# 7. Packing & Shipping Information





All dimensions are in mm MS1V-T1K\_Tape-drw\_20170207

#### **Cover Tape:**

Tape: Polypropylene, 3M™ Universal Cover Tape (UCT) Adhesive Type: Pressure sensitive, Synthetic Polymer

Direction of feed

Thickness: 0.061 mm

#### **Peel Method:**

Medial section removal, both lateral stripes remain on carrier

#### 8. Compliance Information

Micro Crystal confirms that the standard product Quartz Crystal Unit MS1V-T1K is compliant with "EU RoHS Directive" and "EU REACh Directives".

Please find the actual Certificate of Conformance for Environmental Regulations on our website: CoC\_Environment\_MS-Series.pdf

### 9. Document Revision History

Date	Revision #	Revision Details
February 2017	1.0	First release

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